





٨	PART NUMBER PRESS-FIT TAIL SHORT DETECT CONTACT 10076222-101 TIN LEAD ALLOY OVER NICKEL NO TIN OVER	5 6 7 8
А	10076222-101LF NICKEL NO (LEAD FREE) TIN LEAD ALLOY OVER NICKEL YES	
	TIN OVER 10076222-111LF NICKEL YES (LEAD FREE)	
В	NOTES: I. CONNECTOR MATERIALS: HOUSING: HIGH TEMP THERMOPLASTIC, BLACK, UL94V-0 IMLA PLASTIC: HIGH TEMP THERMOPLASTIC, BLACK, UL94V-0 CONTACT: COPPER ALLOY	
	2. CONTACT PLATING: SEPARABLE INTERFACE: PERFORMANCE-BASED PLATING, QUALIFIED TO MEET THE REQUIREMENTS OF FCI PRODUCT SPECIFICATION GS-I2-452 INCLUDING TELCORDIA GR-I2I7-CORE (NOVEMBER 1995) CENTRAL OFFICE TEST SEQUENCE PRESS-FIT TAILS: SEE TABLE	
С	 3. PRODUCT SPECIFICATION: GS-12-452. 4. APPLICATION SPECIFICATION: GS-20-094. 5. PRODUCT MARKING, (PART NUMBER & LOT CODE), ON THESE SURFACES. 6. FOR NON-ORTHOGONAL APPLICATIONS, THE MINIMUM CENTERLINE SPACING BETWEEN ADJACENT MODULES IS 21.6mm. 7. THERE IS NO GROUND BUSSING WITHIN THE HEADER CONNECTOR. HOWEVER, POSITIONS RI, R3, R5, R7, R9, & RII OF THE MATING RECEPTACLE ARE BUSSED. THESE MUST BE ASSIGNED AS GROUNDS. 	
D	THESE MUST BE ASSIGNED AS GROUNDS. 8) REFER TO CUSTOMER DRAWING 10045979 FOR INFORMATION ON PCB HOLE DIAMETERS AND PLATING OPTIONS. 9. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008. 10. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 40 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN. 11. PACKAGING MEETS GS-14-920 LEAD FREE LABELING SPECIFICATION. (12) MINIMUM PCB THICKNESS TO BE 3.5mm FOR ORTHOGONAL APPLICATIONS. (13) CONNECTOR OUTLINE WITH HOUSING POS AI INDICATOR MAY BE SCREEN PRINTED ONTO CUSTOMER PCB TO BE USED AS A GUIDE FOR MANUAL CONNECTOR PLACEMENT. (14) FOR -IIX ASSEMBLIES, MATING PIN J7 HAS 0.60 mm LESS NOMINAL WIPE THAN OTHER PINS.	10076222-1X1
ľ	REV F - 2006-04-17	FS)

CUSTOMER sheet 4 of 4 PDM: Rev:A STATUS: Released 8 Printed: Dec 01, 2010